# ne<mark>x</mark>peria

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Should be replaced with:

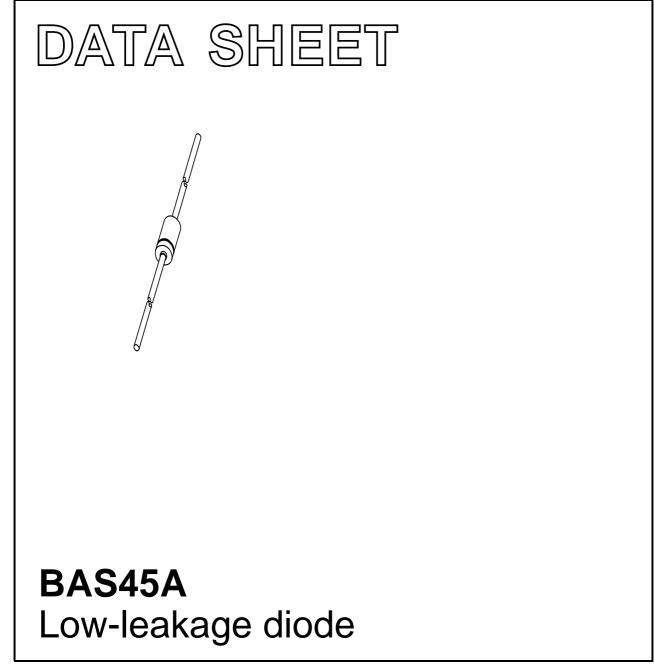
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If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via **salesaddresses@nexperia.com**). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

# DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of June 1994 1996 Mar 13



#### Product data sheet

## Low-leakage diode

## BAS45A

#### FEATURES

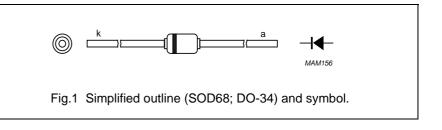
- Continuous reverse voltage: max. 125 V
- Repetitive peak forward current: max. 625 mA
- Low reverse current: max. 1 nA
- Switching time: typ. 1.5  $\mu$ s.

#### APPLICATION

• Low leakage current applications.

#### DESCRIPTION

Epitaxial medium-speed switching diode with a low leakage current in a hermetically-sealed glass SOD68 (DO-34) package.



#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>RRM</sub>	repetitive peak reverse voltage		-	125	V
V <sub>R</sub>	continuous reverse voltage		_	125	V
I <sub>F</sub>	continuous forward current	see Fig.2; note 1	-	250	mA
I <sub>FRM</sub>	repetitive peak forward current		-	625	mA
I <sub>FSM</sub>	non-repetitive peak forward current	square wave; T <sub>j</sub> = 25 °C prior to surge; see Fig.4			
		$t_p = 1 \ \mu s$	-	4	А
		t <sub>p</sub> = 1 ms	_	1	А
		t <sub>p</sub> = 1 s	_	0.5	А
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = 25 °C	_	300	mW
T <sub>stg</sub>	storage temperature		-65	+175	°C
Т <sub>ј</sub>	junction temperature		_	175	°C

#### Note

1. Device mounted on a printed-circuit board without metallization pad.

BAS45A

#### ELECTRICAL CHARACTERISTICS

 $T_j = 25 \ ^{\circ}C$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V <sub>F</sub>	forward voltage	see Fig.3			
		I <sub>F</sub> = 1 mA	_	780	mV
		I <sub>F</sub> = 10 mA	-	860	mV
		I <sub>F</sub> = 100 mA	-	1000	mV
I <sub>R</sub>	reverse current	see Fig.5			
		V <sub>R</sub> = 125 V; E <sub>max</sub> = 100 lx	—	1	nA
		$V_R = 30 \text{ V}; \text{ T}_j = 125 \text{ °C}; \text{ E}_{max} = 100 \text{ Ix}$	—	300	nA
		$V_R = 125 \text{ V}; \text{ T}_j = 125 \text{ °C}; \text{ E}_{max} = 100 \text{ Ix}$	-	500	nA
		$V_R = 125 \text{ V}; \text{ T}_j = 150 \text{ °C}; \text{ E}_{max} = 100 \text{ Ix}$	-	2	μΑ
C <sub>d</sub>	diode capacitance	$f = 1 \text{ MHz}; V_R = 0; \text{ see Fig.6}$	-	4	pF
t <sub>rr</sub>	reverse recovery time	when switched from $I_F = 10$ mA to $I_R = 10$ mA; $R_L = 100 \Omega$ ; measured at $I_R = 1$ mA; see Fig.7	1.5	_	μs

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-tp</sub>	thermal resistance from junction to tie-point	8 mm from the body	300	K/W
R <sub>th j-a</sub>	thermal resistance from junction to ambient	lead length 10 mm; note 1	500	K/W

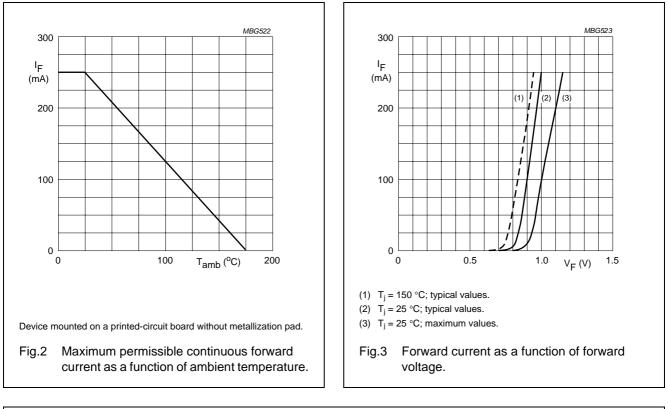
#### Note

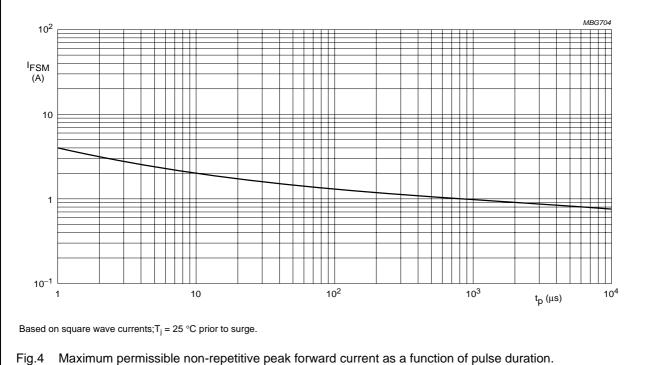
1. Device mounted on a printed-circuit board without metallization pad.

#### Product data sheet

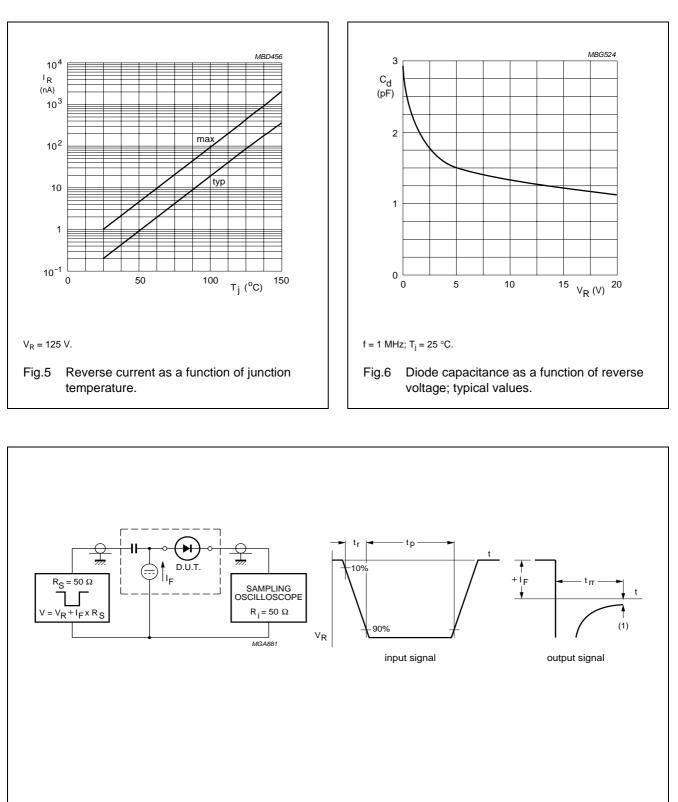
## BAS45A







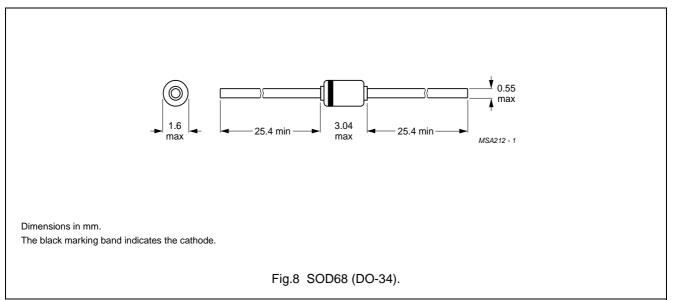
## BAS45A





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#### PACKAGE OUTLINE



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#### DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
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# **NXP Semiconductors**

#### **Customer notification**

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#### **Contact information**

For additional information please visit: http://www.nxp.com For sales offices addresses send e-mail to: salesaddresses@nxp.com

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